

Day : Friday Date: 10/17/2008 Time: 14:48.56

Inventor Name Search Result Office of Public Affairs

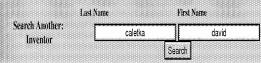
Your Search was:

Last Name = CALETKA First Name = DAVID

Application#	Patent#	PG Pub#	Status	Date Filed	Title	Examiner Name	Inventor Name
12010335	Not Issued	20080142258	025	01/24/2008	HIGH SPEED INTERPOSER		CALETKA, DAVID V,
<u>11152048</u>	7253518	20060284304	150		WIREBOND ELECTRONIC PACKAGE WITH ENHANCED CHIP PAD DESIGN, METHOD OF MAKING SAME, AND INFORMATION HANDLING SYSTEM UTILIZING SAME	HA,NATHAN	CALETKA, DAVID V.
<u>12010469</u>	Not Issued	20080120835	025	\$	METHOD OF MAKING HIGH SPEED INTERPOSER		CALETKA, DAVID V.
11822573	Not Issued	20070254408	030		METHOD OF MAKING WIREBOND ELECTRONIC PACKAGE WITH ENHANCED CHIP PAD DESIGN	FAHMY,WAEL	CALETKA, DAVID V.
09570895	6410988		150		THERMALLY ENHANCED AND MECHANICALLY BALANCED FLIP CHIP PACKAGE AND METHOD OF FORMING	LE,BAU	CALETKA, DAVID V.
09605173	6603195		150		PLANARIZED PLASTIC PACKAGE MODULES FOR INTEGRATED CIRCUITS	WILLIAMS, ALEXANDER	CALETKA, DAVID V.
09649318	6293455		150	4	METHOD FOR PRODUCING A RELIABLE BGA SOLDER JOINT INTERCONNECTION	DUNN,COLLEEN	CALETKA, DAVID V.
10692921	Not Issued	20050089264	077		PASSIVE ALIGNMENT OF VCSELS TO WAVEGUIDES IN OPTO-ELECTRONIC CARDS AND PRINTED CIRCUIT BOARDS	HEALY,BRIAN	CALETKA, DAVID V.
<u>10717946</u>	6913948	20040099936	150		PARTIALLY CAPTURED ORIENTED INTERCONNECTIONS FOR BGA PACKAGES AND A METHOD OF FORMING THE INTERCONNECTIONS	MITCHELLJAMES	CALETKA, DAVID V.
10273786	6933619	20030034569	150	3	ELECTRONIC PACKAGE AND METHOD OF FORMING	ANDUJAR,LEONARDO	CALETKA, DAVID V.
10215451	6649833	0	150		NEGATIVE VOLUME EXPANSION LEAD-FREE ELECTRICAL CONNECTION	NGO,HUNG	CALETKA, DAVID V.
09871554	6695623	20020182900	150	\$	ENHANCED ELECTRICAL/MECHANICAL CONNECTION FOR ELECTRONIC DEVICES	GILMAN,ALEXANDER	CALETKA, DAVID V.
09801948	6672500	20010045445	250	5	METHOD FOR PRODUCING A RELIABLE SOLDER JOINT INTERCONNECTION	EDMONDSON,LYNNE	CALETKA, DAVID V.
09860549	6433283	20010020541	150	05/21/2001	DUAL PURPOSE RIBBON CABLE	NGUYEN,CHAU	CALETKA, DAVID V.

11454896	Not Issued	20070289773	041	06/19/2006	HIGH SPEED INTERPOSER	PATEL,ISHWARBHAI	CALETKA, DAVID V.
09656941	6333551		150		SURFACE PROFILING IN ELECTRONIC PACKAGES FOR REDUCING THERMALLY INDUCED INTERFACIAL STRESSES	CLARK,SHEILA	CALETKA, DAVID V.
09754782	6541857	20010000925	150	3	METHOD OF FORMING BGA INTERCONNECTIONS HAVING MIXED SOLDER PROFILES	LEE,EUGENE	CALETKA, DAVID V.
09491066	6268567		250	01/25/2000	DUAL PURPOSE RIBBON CABLE	NGUYEN,CHAU	CALETKA, DAVID V.
12015604	Not Issued	20080119029	030	01/17/2008	WAFER SCALE THIN FILM PACKAGE	GRAYBILL,DAVID	CALETKA, DAVID VINCENT
10336579	6905961	20030090000	150		LAND GRID ARRAY STIFFENER FOR USE WITH FLEXIBLE CHIP CARRIERS	THALLUAN	CALETKA, DAVID VINCENT
11440316	Not Issued	20060208030	061		METHOD TO ACCOMMODATE INCREASE IN VOLUME EXPANSION DURING SOLDER REFLOW	NGUYEN,DONGHAI	CALETKA, DAVID VINCENT
09626904	6627998		150	07/27/2000	WAFER SCALE THIN FILM PACKAGE	WILLIAMS,ALEXANDER	CALETKA, DAVID VINCENT
09845448	6686664	20020158110	150		STRUCTURE TO ACCOMMODATE INCREASE IN VOLUME EXPANSION DURING SOLDER REFLOW	TRINH,HOA	CALETKA, DAVID VINCENT
09874196	6528892	20020180061	150	3	LAND GRID ARRAY STIFFENER USE WITH FLEXIBLE CHIP CARRIERS	THALLUAN	CALETKA, DAVID VINCENT
09855308	6595784	20020173175	150		INTERPOSER MEMBER HAVING APERTURES FOR RELIEVING STRESS AND INCREASING CONTACT COMPLIANCY	HAMMOND,BRIGGITTE	CALETKA, DAVID VINCENT
10768836	7086147	20040183094	150		STRUCTURE TO ACCOMMODATE INCREASE IN VOLUME EXPANSION DURING SOLDER REFLOW	NGUYEN,DONGHAI	CALETKA, DAVID VINCENT
10438947	7348261	20030199121	150	05/15/2003	WAFER SCALE THIN FILM PACKAGE	GRAYBILL,DAVID	CALETKA, DAVID VINCENT

Inventor Search Completed: No Records to Display.



Enter both names for a faster result, even if it is only a few letters.

(To go back use Back button on your browser toolbar)